



YETDA INDUSTRY LTD.

Technical Data Sheet

MODEL NO : S776ANW4P-M-18V

2835 Package 2.8*3.5*0.7mm Chip LEDs

Features :

- Compatible with automatic placement equipment
- Compatible with reflow solder process

Applications :

- Indicators
- Automotive : backlighting in dashboard and switch
- Backlight for LCD

Dice material	Emitted color	Lens Color
InGaN	White	Water Clear

Electrical/Optical Characteristics(Ta=25°C)

Parameter	Test Condition	Symbol	Value			Unit
			Min	Typ	Max	
Color Coordinates	If=60mA	x		0.313		
		y		0.3337		
Forward voltage	If=60mA	Vf	17		21	V
Luminous flux (lm)	If=60mA	lm	100	110		
Color Temperature	If=60mA	CCT		6000		K
Color Rendering Index	If=60mA	Ra	80			
Viewing angle at 50% Iv	If=60mA	2 θ 1/2		120		Deg
Reverse current	Vr=5V	Ir			10	μA

Absolute Maximum Ratings(Ta=25°C)

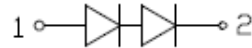
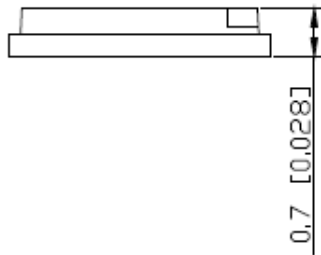
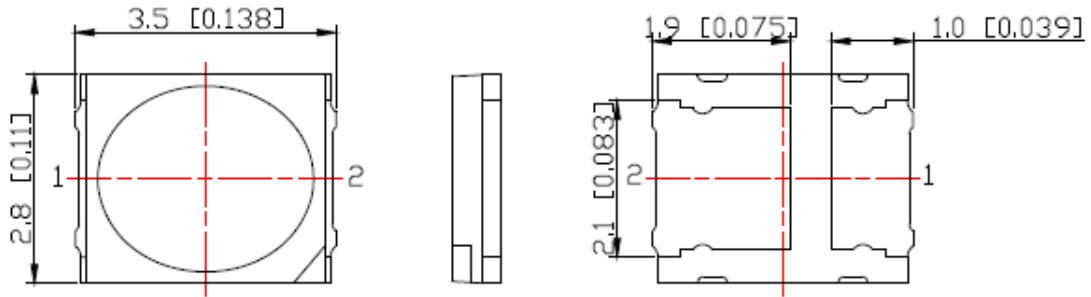
Parameter	Symbol	Value	Unit
Power dissipation	Pd	600	mW
Forward current	If	60	mA
Reverse voltage	Vr	30	V
Operating temperature range	Top	-40 ~+85	°C
Storage temperature range	Tstg	-40 ~+85	°C
Peak pulsing current (1/8 duty f=1kHz)	Ifp	100	mA

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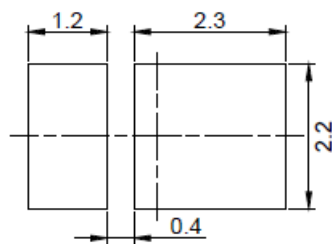


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PACKAGING DIMENSIONS

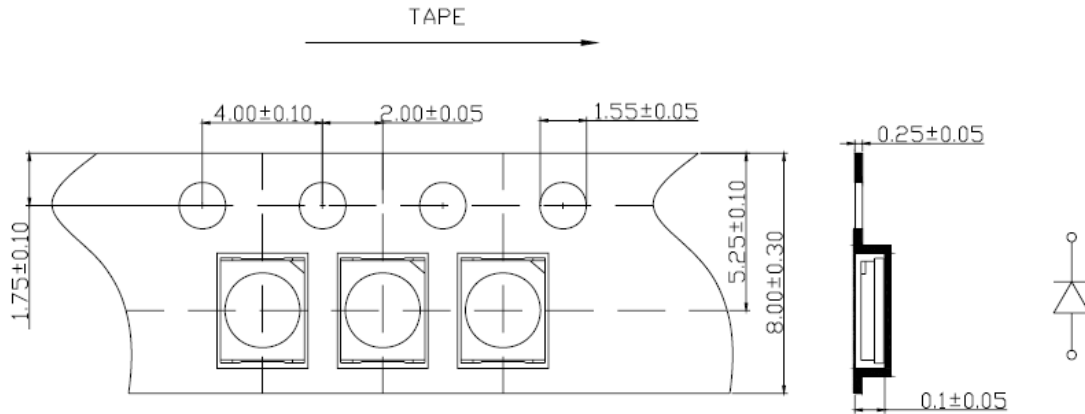


RECOMMENDED SOLDERING PATTERN





TAPE SPECIFICATIONS

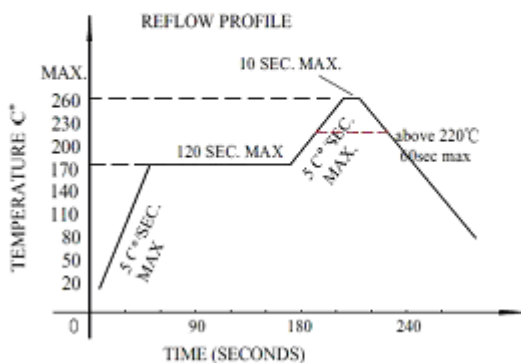


Precautions For Use :
Over - current - proof
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)
Storage
1. The operation of temperature and R.H. are : 5°C ~ 30°C , 60%R.H. Max.
2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date) .
3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : 60°C±5°C for 15hrs.

■ Reflow Temp/Time

■ Temperature-profile (Surface of circuit board)

Use the following conditions shown in the figure.





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NOTES:

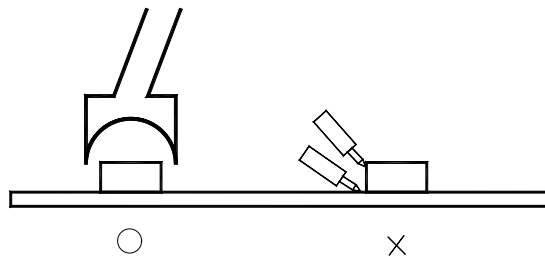
1. We recommend the reflow temperature $245^{\circ}\text{C}(\pm 5^{\circ}\text{C})$.the maximum soldering temperature should be limited to 260°C .
2. dont cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

■Soldering iron

Basic spec is $\leq 5\text{sec}$ when 260°C . If temperature is higher, time should be shorter ($+10^{\circ}\text{C} \rightarrow -1\text{sec}$).Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under 230°C .

■Rework

1. Customer must finish rework within 5 sec under 260°C .
2. The head of iron can not touch copper foil
3. Twin-head type is preferred.



- Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow 、 solder etc.